



Product End-of-Life Disassembly Instructions

Product Category: Notebooks

Marketing Name / Model
[List multiple models if applicable.]

HP EliteBook 665 16 inch G11 Notebook PC

HSN-Q39C-6

HP EliteBook 665 16 inch G11 Notebook PC (ENERGY STAR)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact [HP's Sustainability Contact](#).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	<input checked="" type="checkbox"/> Main board (MB) PCB <input type="checkbox"/> Solid state drive (SSD) PCB <input checked="" type="checkbox"/> Wireless WAN module (WWAN) PCB <input type="checkbox"/> Touch module PCB <input type="checkbox"/> Power supply PCB <input type="checkbox"/> External Keyboard (KB) <input type="checkbox"/> External Mouse <input checked="" type="checkbox"/> Others: IO board _____	3
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	<input type="checkbox"/> RTC/CMOS battery <input type="checkbox"/> Others: _____	
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: <input checked="" type="checkbox"/> screws <input checked="" type="checkbox"/> snaps <input type="checkbox"/> adhesive <input type="checkbox"/> other. Explain _____	1
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	Battery,LCD	2
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	<input checked="" type="checkbox"/> Panel LCD	1
Cathode Ray Tubes (CRT)		0

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HP Inc. instructions for this template are available at [EL-MF877-01](#)

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	<input type="checkbox"/> Power Supply capacitor(s) or condenser(s)	0
External electrical cables and cords	<input checked="" type="checkbox"/> AC power cord <input type="checkbox"/> Audio, video or data cables <input type="checkbox"/> Other: _____	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	Philip #0
Screwdriver	Torx T8
Heatgun	N/A
Suction cup	N/A

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. Use screwdriver to release base cover #1 screw 5PCS
2. Slider out from R to L side to release battery
3. Use screwdriver to release main board #1 screw 9PCS
4. Release below cable: Speaker cable, Finger Printer cable, backlight cable, TP cable , SD card cable, KB Cable ,EDP cable , WLAN antenna cable. And Disassemble I/O holder, RJ-45. Final step release main board

5. Release hinge screw with screwdriver
6. Set Hinge UP to 90 degree and release hinge up

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: [End-of-Life Product Disassembly Instructions \(hp.com\)](http://End-of-Life Product Disassembly Instructions (hp.com))

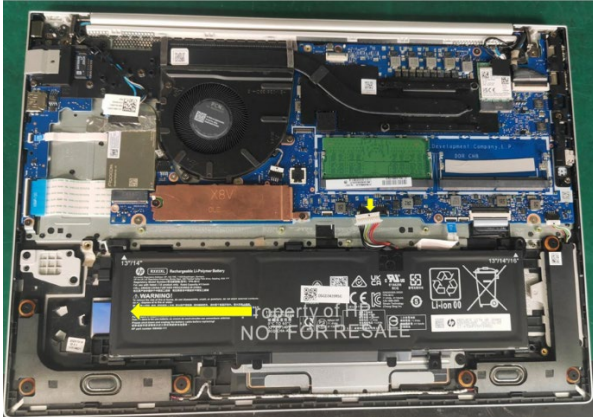
3.21 Use screwdriver to release base cover #1 screw
5PCS



And disassemble base cover from hinge side

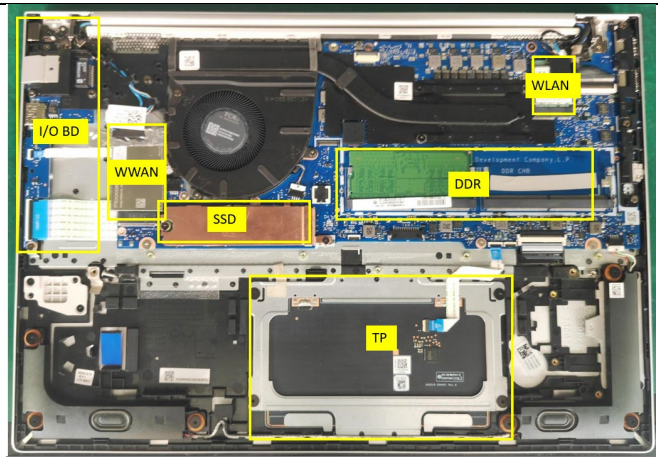
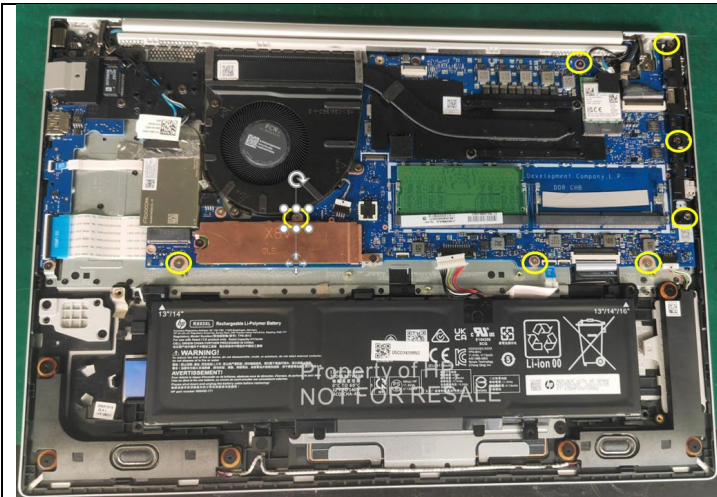


3.22 Slider out from R to L side to release battery

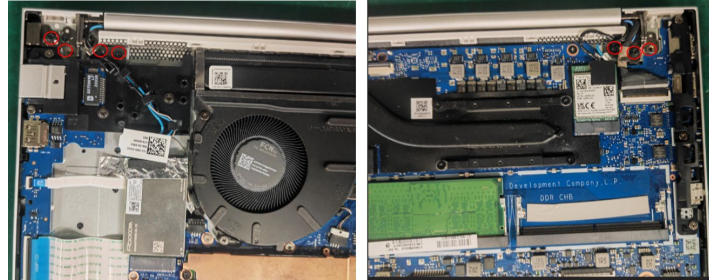


3.23 Use screwdriver to release main board #1 screw
9PCS

3.24 Release below cable: Speaker cable, Finger Printer cable, backlight cable, TP cable, SD card cable, KB Cable, EDP cable, WLAN antenna cable. And Disassemble I/O holder, RJ-45. Final step release main board



3.25 release hinge screw with screwdriver



3.26 Set Hinge UP to 90 degree and release hinge up

